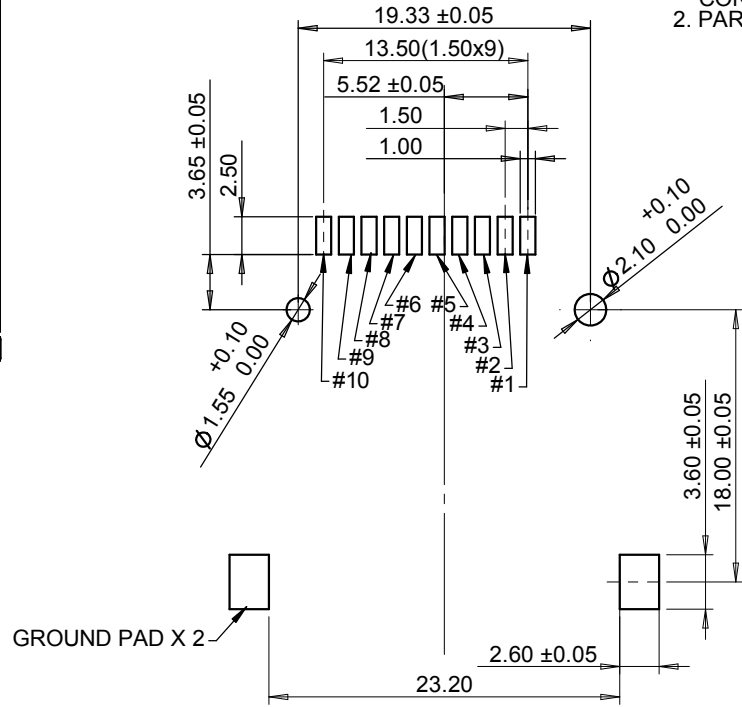
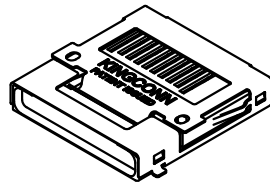


更改 REV	設 變 內 容 MODIFICATION
A	ECN00380
B	ECN00501
C	ECN00900

NOTES :
 1. MATERIAL :
 INSULATOR : HIGH TEMPRATURE THERMOPLASTIC,
 UL 94V-0, IVORY
 CONTACT : COPPER ALLOY
 2. PART NO : MSMS-X9-0110

PLATING :
 F CONTACT AREA : GOLD FLASH Au Plated OVER Ni
 SOLDER AREA : Tin/Lead Plated OVER Ni
 B CONTACT AREA : 10µ" Au Plated OVER Ni
 SOLDER AREA : Tin Plated OVER Ni



PIN DEFINITION

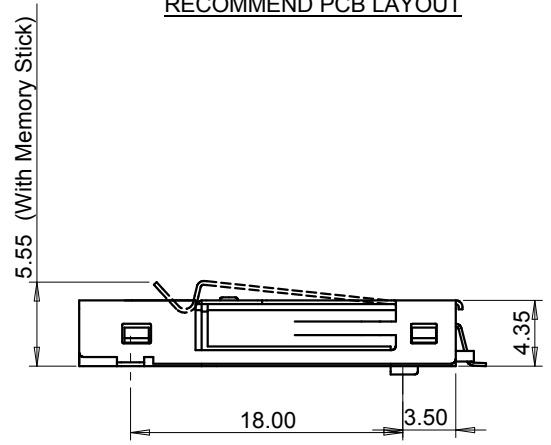
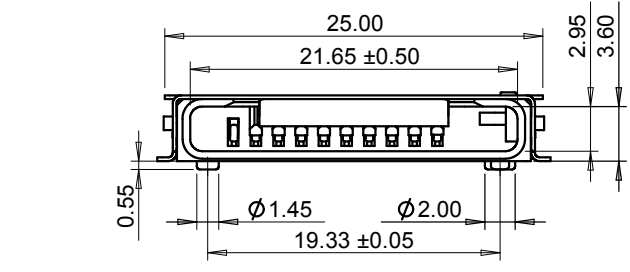
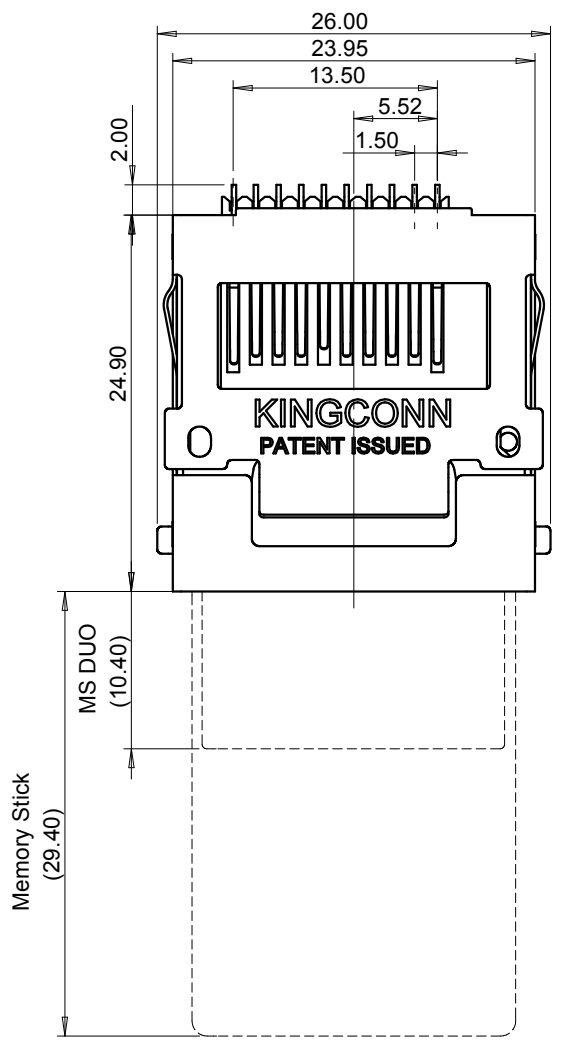
MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS

GENERAL TOLERANCE	
X ± 0.50	X° ± 5°
.X ± 0.30	.X° ± 2°
.XX ± 0.20	.XX° ± 1°

KINGCONN 皇海科技股份有限公司

名稱(TITLE) MemoryStick & MemoryStick Duo Connector Reverse type

單位(UNIT) mm	料 號(PART NO.) MSMS-X9-0110	圖 號(DWG NO.) MSMS-X9-0110-C
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)
比 例 SCALE 2:1	張 數 SHEET 1/1	更 改 REV C



Memory Stick
(29.40)

MS DUO
(10.40)

KINGCONN
PATENT ISSUED

RECOMMEND PCB LAYOUT

GROUND PAD X 2

